	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
					USPAT; US-PGPUB;		
1	BRS	L1	1567	257/686 and (bump ball)	EPO; JPO; DERWENT; IBM_TDB	2004/07/24 09:49	
					USPAT; US-PGPUB;		
2	BRS	L2	1243	257/686 and (bump ball) and (wire adj bonding wire)	EPO; JPO; DERWENT; IBM_TDB	2004/07/24 09:50	
3	BRS	L3	191	257/686 and (bump ball) and (wire adj bonding wire) and invert$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 10:18	
4	BRS	L6	28	257/687 and (bump ball) and (wire adj bonding wire) and invert$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 10:19	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
					USPAT; US-PGPUB;		
5	BRS	L7	332	257/687 and (bump ball) and (wire adj bonding wire)	EPO; JPO; DERWENT; IBM_TDB	2004/07/24 10:21	
					USPAT; US-PGPUB;		
6	BRS	L8	1268	257/777 and (bump ball) and (wire adj bonding wire)	EPO; JPO; DERWENT; IBM_TDB	2004/07/24 10:21	
7	BRS	L9	146	257/777 and (bump ball) and (wire adj bonding wire) and inverted	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 10:21	
8	BRS	L10	179	257/777 and (bump ball) and (wire adj bonding wire) and invert$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 10:28	
9	IS&R	L13	0	("stackwith(packageMCMmultadj2chipadjmodule)").PN.	EPO; JPO; DERWENT; IBM_TDB	2004/07/24 10:32	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
10	BRS	L14	4415	stack$4 with(package MCM mult adj2 chip adj module)	EPO; JPO; DERWENT; IBM_TDB	2004/07/24 10:33	
11	BRS	L15	54	stack$4 with (package MCM mult adj2 chip adj module) and invert$3	EPO; JPO; DERWENT; IBM_TDB	2004/07/24 10:34	
12	BRS	L16	4399	stack$4 with package	EPO; JPO; DERWENT; IBM_TDB	2004/07/24 10:35	
13	BRS	L17	428	stack$4 with package and (wire wire adj bonding)	EPO; JPO; DERWENT; IBM_TDB	2004/07/24 11:13	
14	BRS	L20	41	stack$4 with (MCM multi adj chip adj module) and (wire wire adj bonding)	EPO; JPO; DERWENT; IBM_TDB	2004/07/24 11:15	
15	BRS	L21	2	stack$4 with top adj2 (carrier board substrate) same bottom adj2 (carrier board substrate) same (wire wire adj bonding)	EPO; JPO; DERWENT; IBM_TDB	2004/07/24 11:16	
16	BRS	L22	4	stack$4 with upper adj2 (carrier board substrate) same lower adj2 (carrier board substrate) same (wire wire adj bonding)	EPO; JPO; DERWENT; IBM_TDB	2004/07/24 11:17	
17	BRS	L23	0	257/$.ccls. and stack$4 with (upper top) adj2 (carrier board substrate) same (lower bottom) adj2 (carrier board substrate) same (wire wire adj bonding)	EPO; JPO; DERWENT; IBM_TDB	2004/07/24 11:17	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
18	BRS	L24	5	257/$.ccls. and stack$4 with (upper top) adj2 (carrier board substrate) same (lower bottom) adj2 (carrier board substrate) same (wire wire adj bonding)	USPAT	2004/07/24 11:18	
19	BRS	L25	2	361/$.ccls. and stack$4 with (upper top) adj2 (carrier board substrate) same (lower bottom) adj2 (carrier board substrate) same (wire wire adj bonding)	USPAT	2004/07/24 11:19	
20	BRS	L26	1	438/$.ccls. and stack$4 with (upper top) adj2 (carrier board substrate) same (lower bottom) adj2 (carrier board substrate) same (wire wire adj bonding)	USPAT	2004/07/24 11:19	
21	BRS	L27	19	361/$.ccls. and stack$4 with (upper top) adj2 (carrier board substrate) same (lower bottom) adj2 (carrier board substrate) and (wire wire adj bonding)	USPAT	2004/07/24 11:20	
22	BRS	L28	25	257/$.ccls. and stack$4 with (upper top) adj2 (carrier board substrate) same (lower bottom) adj2 (carrier board substrate) and (wire wire adj bonding)	USPAT	2004/07/24 11:21	
23	BRS	L29	52	257/674 and stack$4	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 11:36	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
24	BRS	L30	493	257/685 and (wire wire adj bonding) and (ball bump)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 11:32	
25	BRS	L31	396	257/685 and (wire wire adj bonding) and (ball bump) and lead	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 11:32	
26	BRS	L32	576	257/674	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 11:39	
27	BRS	L33	1610	257/738 and lead	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 11:40	
28	BRS	L34	446	257/738 and lead adj frame	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 11:46	
29	BRS	L35	378	257/696 and (ball bump)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 12:01	